

# CAT25C08, CAT25C16

8K/16K SPI Serial CMOS EEPROM

## FEATURES

- 10 MHz SPI compatible
- 1.8 to 5.5 volt operation
- 32-byte page write buffer
- Hardware and software protection
- Block write protection
  - Protect 1/4, 1/2 or all of EEPROM array
- Low power CMOS technology
- SPI modes (0,0 & 1,1)
- Industrial temperature range
- 1,000,000 program/erase cycles
- 100 year data retention
- Self-timed write cycle
- RoHS compliant “Green” & “Gold”  
8-pin PDIP, SOIC and TSSOP packages available

## DESCRIPTION

The CAT25C08/16 is a 8K/16K Bit SPI Serial CMOS EEPROM internally organized as 1024x8/2048x8 bits. Catalyst’s advanced CMOS Technology substantially reduces device power requirements. The CAT25C08/16 features a 32-byte page write buffer. The device operates via the SPI bus serial interface and is enabled through a Chip Select ( $\overline{CS}$ ). In addition to the Chip Select, the clock input (SCK), data in (SI) and data out (SO) are required to access the device. The  $\overline{HOLD}$  pin may be used to suspend any serial communication without resetting the serial sequence. The CAT25C08/16 is designed with software and hardware write protection features including Block Write protection. The device is available in 8-pin DIP, 8-pin SOIC and 8-pin TSSOP packages.

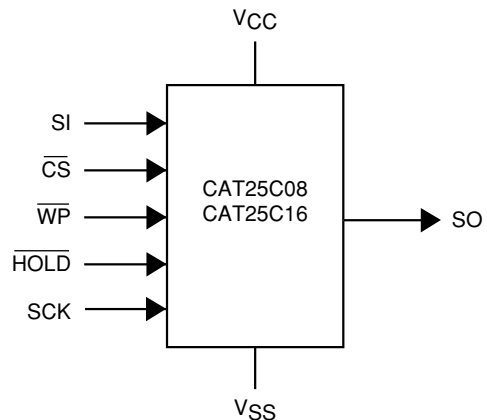
## PIN CONFIGURATION

	PDIP (P, L)		
	SOIC (S, V)		
	TSSOP (U, Y)		
$\overline{CS}$	1	8	VCC
SO	2	7	$\overline{HOLD}$
$\overline{WP}$	3	6	SCK
VSS	4	5	SI

## PIN FUNCTIONS

Pin Name	Function
SO	Serial Data Output
SCK	Serial Clock
$\overline{WP}$	Write Protect
VCC	+1.8V to +5.5V Power Supply
VSS	Ground
$\overline{CS}$	Chip Select
SI	Serial Data Input
$\overline{HOLD}$	Suspends Serial Input

## FUNCTIONAL SYMBOL



**ABSOLUTE MAXIMUM RATINGS\***

Temperature Under Bias .....	-55°C to +125°C
Storage Temperature .....	-65°C to +150°C
Voltage on any Pin with Respect to $V_{SS}^{(1)}$ .....	-2.0V to $+V_{CC} + 2.0V$
$V_{CC}$ with Respect to $V_{SS}$ .....	-2.0V to +7.0V
Package Power Dissipation Capability ( $T_a = 25^\circ\text{C}$ ) .....	1.0W
Lead Soldering Temperature (10 secs) .....	300°C
Output Short Circuit Current <sup>(2)</sup> .....	100 mA

**\*COMMENT**

Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions outside of those listed in the operational sections of this specification is not implied. Exposure to any absolute maximum rating for extended periods may affect device performance and reliability.

**RELIABILITY CHARACTERISTICS**

Symbol	Parameter	Min.	Typ.	Max.	Units
$N_{END}^{(3)}$	Endurance	1,000,000			Cycles/Byte
$T_{DR}^{(3)}$	Data Retention	100			Years
$V_{ZAP}^{(3)}$	ESD Susceptibility	2000			Volts
$I_{LTH}^{(3)(4)}$	Latch-up	100			mA

**D.C. OPERATING CHARACTERISTICS**

$V_{CC} = +1.8V$  to  $+6.0V$ , unless otherwise specified.

Symbol	Parameter	Limits			Units	Test Conditions
		Min.	Typ.	Max.		
$I_{CC1}$	Power Supply Current (Operating Write)			5	mA	$V_{CC} = 5V @ 5MHz$ $SO=open; CS=V_{SS}$
$I_{CC2}$	Power Supply Current (Operating Read)			3	mA	$V_{CC} = 5.5V$ $F_{CLK} = 5MHz$
$I_{SB}^{(6)}$	Power Supply Current (Standby)			1	$\mu A$	$\overline{CS} = V_{CC}$ $V_{IN} = V_{SS}$ or $V_{CC}$
$I_{LI}$	Input Leakage Current			2	$\mu A$	
$I_{LO}$	Output Leakage Current			3	$\mu A$	$V_{OUT} = 0V$ to $V_{CC}$ , $CS = 0V$
$V_{IL}^{(5)}$	Input Low Voltage	-1		$V_{CC} \times 0.3$	V	
$V_{IH}^{(5)}$	Input High Voltage	$V_{CC} \times 0.7$		$V_{CC} + 0.5$	V	
$V_{OL1}$	Output Low Voltage			0.4	V	$2.7V \leq V_{CC} < 5.5V$ $I_{OL} = 3.0mA$ $I_{OH} = -1.6mA$
$V_{OH1}$	Output High Voltage	$V_{CC} - 0.8$			V	
$V_{OL2}$	Output Low Voltage			0.2	V	$1.8V \leq V_{CC} < 2.7V$ $I_{OL} = 150\mu A$ $I_{OH} = -100\mu A$
$V_{OH2}$	Output High Voltage	$V_{CC} - 0.2$			V	

**Note:**

- The minimum DC input voltage is  $-0.5V$ . During transitions, inputs may undershoot to  $-2.0V$  for periods of less than 20 ns. Maximum DC voltage on output pins is  $V_{CC} + 0.5V$ , which may overshoot to  $V_{CC} + 2.0V$  for periods of less than 20 ns.
- Output shorted for no more than one second. No more than one output shorted at a time.
- These parameter are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.
- Latch-up protection is provided for stresses up to 100 mA on address and data pins from  $-1V$  to  $V_{CC} + 1V$ .
- $V_{ILMIN}$  and  $V_{IHMAX}$  are reference values only and are not tested.
- Maximum standby current ( $I_{SB}$ ) =  $10\mu A$  for the Automotive and Extended Automotive temperature range.

**PIN CAPACITANCE (1)**

 Applicable over recommended operating range from  $T_A=25^{\circ}\text{C}$ ,  $f=1.0\text{ MHz}$ ,  $V_{CC}=\pm 5.0\text{V}$  (unless otherwise noted).

Symbol	Test Conditions	Max.	Units	Conditions
$C_{OUT}$	Output Capacitance (SO)	8	pF	$V_{OUT}=0\text{V}$
$C_{IN}$	Input Capacitance ( $\overline{CS}$ , SCK, SI, $\overline{WP}$ , $\overline{HOLD}$ )	6	pF	$V_{IN}=0\text{V}$

**A.C. CHARACTERISTICS**

SYMBOL	PARAMETER	CAT25Cxx-1.8		CAT25Cxx				UNITS	Test Conditions
		1.8V-5.5V		2.5V-5.5V		4.5V-5.5V			
		Min.	Max.	Min.	Max.	Min.	Max.		
$t_{SU}$	Data Setup Time	50		20		20		ns	C <sub>L</sub> = 50pF (2)
$t_{H}$	Data Hold Time	50		20		20		ns	
$t_{WH}$	SCK High Time	250		75		40		ns	
$t_{WL}$	SCK Low Time	250		75		40		ns	
$f_{SCK}$	Clock Frequency	DC	1	DC	5	DC	10	MHz	
$t_{LZ}$	$\overline{HOLD}$ to Output Low Z		50		50		50	ns	
$t_{RI}^{(1)}$	Input Rise Time		2		2		2	μs	
$t_{FI}^{(1)}$	Input Fall Time		2		2		2	μs	
$t_{HD}$	$\overline{HOLD}$ Setup Time	100		40		40		ns	
$t_{CD}$	$\overline{HOLD}$ Hold Time	100		40		40		ns	
$t_{WC}^{(3)}$	Write Cycle Time		10		5		5	ms	
$t_V$	Output Valid from Clock Low		250		75		40	ns	
$t_{HO}$	Output Hold Time	0		0		0		ns	
$t_{DIS}$	Output Disable Time		250		75		75	ns	
$t_{HZ}$	$\overline{HOLD}$ to Output High Z		150		50		50	ns	
$t_{CS}$	$\overline{CS}$ High Time	500		100		100		ns	
$t_{CSS}$	$\overline{CS}$ Setup Time	500		100		100		ns	
$t_{CSH}$	$\overline{CS}$ Hold Time	500		100		100		ns	
$t_{WPS}$	$\overline{WP}$ Setup Time	150		50		50		ns	
$t_{WPH}$	$\overline{WP}$ Hold Time	150		50		50		ns	

**Power-Up Timing<sup>(4)(5)</sup>**

Symbol	Parameter	Max.	Units
$t_{PUR}$	Power-up to Read Operation	1	ms
$t_{PUW}$	Power-up to Write Operation	1	ms

**NOTE:**

- (1) This parameter is tested initially and after a design or process change that affects the parameter.
- (2) AC Test Conditions:  
 Input Pulse Voltages:  $0.3V_{CC}$  to  $0.7V_{CC}$   
 Input rise and fall times:  $\leq 10\text{ns}$   
 Input and output reference voltages:  $0.5V_{CC}$   
 Output load: current source  $I_{OL\text{ max}}$ / $I_{OH\text{ max}}$ ;  $C_L = 50\text{pF}$
- (3)  $t_{WC}$  is the time from the rising edge of  $\overline{CS}$  after a valid write sequence to the end of the internal write cycle.
- (4) This parameter is tested initially and after a design or process change that affects the parameter.
- (5)  $t_{PUR}$  and  $t_{PUW}$  are the delays required from the time  $V_{CC}$  is stable until the specified operation can be initiated.

## FUNCTIONAL DESCRIPTION

The CAT25C08/16 supports the SPI bus data transmission protocol. The synchronous Serial Peripheral Interface (SPI) helps the CAT25C08/16 to interface directly with many of today's popular microcontrollers. The CAT25C08/16 contains an 8-bit instruction register. (The instruction set and the operation codes are detailed in the instruction set table)

After the device is selected with  $\overline{CS}$  going low, the first byte will be received. The part is accessed via the SI pin, with data being clocked in on the rising edge of SCK. The first byte contains one of the six op-codes that define the operation to be performed.

## PIN DESCRIPTION

### SI: Serial Input

SI is the serial data input pin. This pin is used to input all opcodes, byte addresses, and data to be written to the 25C08/16. Input data is latched on the rising edge of the serial clock for SPI modes (0, 0 & 1, 1).

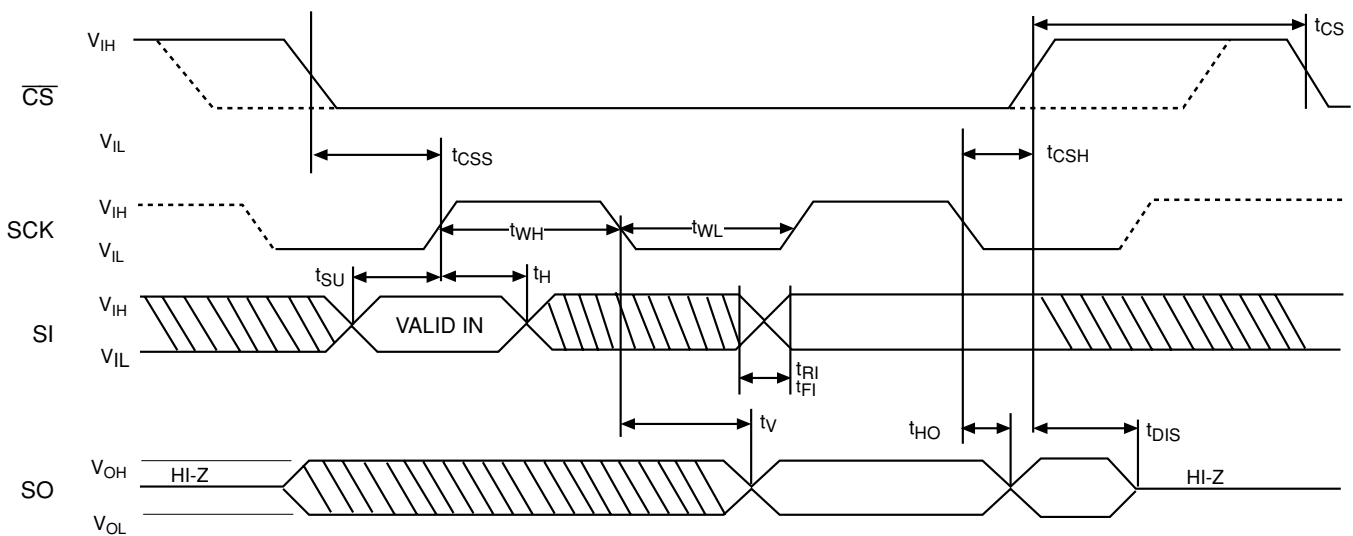
### SO: Serial Output

SO is the serial data output pin. This pin is used to transfer data out of the 25C08/16. During a read cycle, data is shifted out on the falling edge of the serial clock for SPI modes (0,0 & 1,1).

### SCK: Serial Clock

SCK is the serial clock pin. This pin is used to synchronize the communication between the microcontroller

**Figure 1. Synchronous Data Timing**



Note: Dashed Line= mode (1, 1) -----

## INSTRUCTION SET

Instruction	Opcode	Operation
WREN	0000 0110	Enable Write Operations
WRDI	0000 0100	Disable Write Operations
RDSR	0000 0101	Read Status Register
WRSR	0000 0001	Write Status Register
READ	0000 0011	Read Data from Memory
WRITE	0000 0010	Write Data to Memory

and the 25C08/16. Opcodes, byte addresses, or data present on the SI pin are latched on the rising edge of the SCK. Data on the SO pin is updated on the falling edge of the SCK for SPI modes (0,0 & 1,1) .

**$\overline{CS}$** : Chip Select

$\overline{CS}$  is the Chip select pin.  $\overline{CS}$  low enables the CAT25C08/16 and  $\overline{CS}$  high disables the CAT25C08/16.  $\overline{CS}$  high

takes the SO output pin to high impedance and forces the devices into a Standby Mode (unless an internal write operation is underway) The CAT25C08/16 draws ZERO current in the Standby mode. A high to low transition on  $\overline{CS}$  is required prior to any sequence being initiated. A low to high transition on  $\overline{CS}$  after a valid write sequence is what initiates an internal write cycle.

### BYTE ADDRESS

Device	Address Significant Bits	Address Don't Care Bits	# Address Clock Pulse
CAT25C08	A9 - A0	A15 - A10	16
CAT25C16	A10 - A0	A15 - A11	16

### STATUS REGISTER

7	6	5	4	3	2	1	0
WPEN	0	1	X	BP1	BP0	WEL	$\overline{RDY}$

### BLOCK PROTECTION BITS

Status Register Bits		Array Address Protected	Protection
BP1	BP0		
0	0	None	No Protection
0	1	25C08: 0300-03FF 25C16: 0600-07FF	Quarter Array Protection
1	0	25C08: 0200-03FF 25C16: 0400-07FF	Half Array Protection
1	1	25C08: 0000-03FF 25C16: 0000-07FF	Full Array Protection

### WRITE PROTECT ENABLE OPERATION

WPEN	$\overline{WP}$	WEL	Protected Blocks	Unprotected Blocks	Status Register
0	X	0	Protected	Protected	Protected
0	X	1	Protected	Writable	Writable
1	Low	0	Protected	Protected	Protected
1	Low	1	Protected	Writable	Protected
X	High	0	Protected	Protected	Protected
X	High	1	Protected	Writable	Writable

**WP:** Write Protect

WP is the Write Protect pin. The Write Protect pin will allow normal read/write operations when held high. When WP is tied low and the WPEN bit in the status register is set to “1”, all write operations to the status register are inhibited. WP going low while CS is still low will interrupt a write to the status register. If the internal write cycle has already been initiated, WP going low will have no effect on any write operation to the status register. The WP pin function is blocked when the WPEN bit is set to 0. Figure 10 illustrates the WP timing sequence during a write operation.

**HOLD:** Hold

HOLD is the HOLD pin. The HOLD pin is used to pause transmission to the CAT25C08/16 while in the middle of a serial sequence without having to re-transmit entire sequence at a later time. To pause, HOLD must be brought low while SCK is low. The SO pin is in a high impedance state during the time the part is paused, and transitions on the SI pins will be ignored. To resume communication, HOLD is brought high, while SCK is low. HOLD should be held high any time this function is not being used. HOLD may be tied high directly to VCC or tied to VCC through a resistor. Figure 9 illustrates hold timing sequence.

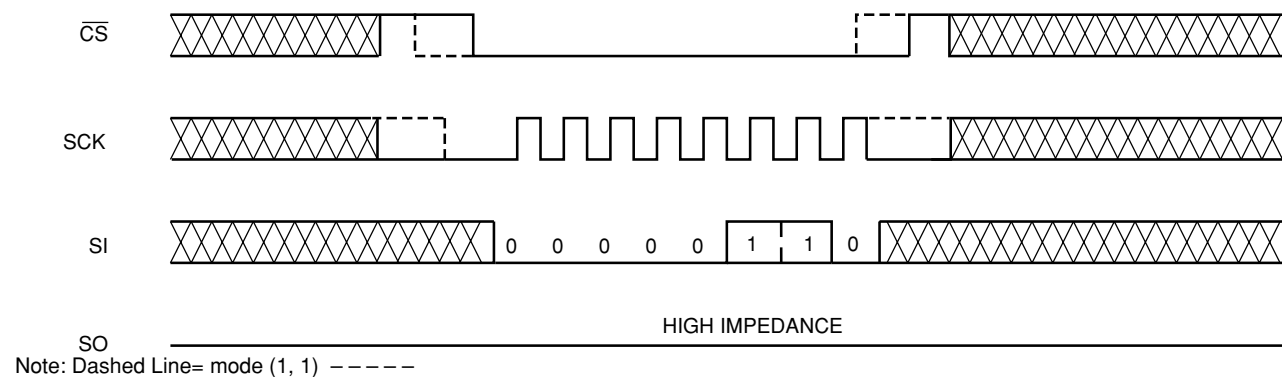
**STATUS REGISTER**

The Status Register indicates the status of the device. The RDY (Ready) bit indicates whether the CAT25C08/16 is busy with a write operation. When set to 1 a write cycle is in progress and when set to 0 the device indicates it is ready. This bit is read only. The WEL (Write Enable) bit indicates the status of the write enable latch. When set to 1, the device is in a Write Enable state and when set to 0 the device is in a Write Disable state. The WEL bit can only be set by the WREN instruction and can be reset by the WRDI instruction.

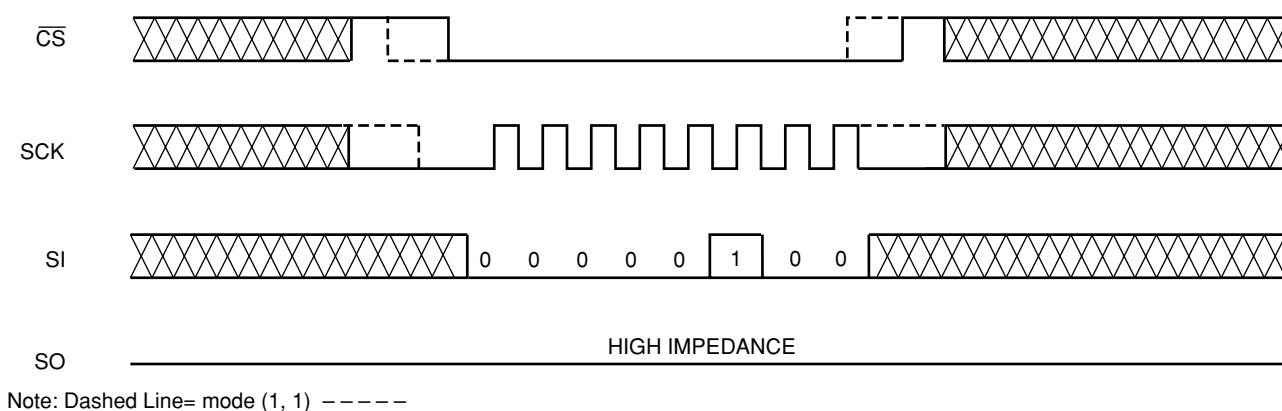
The BP0 and BP1 (Block Protect) bits indicate which blocks are currently protected. These bits are set by the user issuing the WRSR instruction. The user is allowed to protect quarter of the memory, half of the memory or the entire memory by setting these bits. Once protected the user may only read from the protected portion of the array. These bits are non-volatile.

The WPEN (Write Protect Enable) is an enable bit for the WP pin. The WP pin and WPEN bit in the status register control the programmable hardware write protect feature. Hardware write protection is enabled when WP is low and WPEN bit is set to high. The user cannot write to the status register, (including the block protect

**Figure 2. WREN Instruction Timing**



**Figure 3. WRDI Instruction Timing**



bits and the WPEN bit) and the block protected sections in the memory array when the chip is hardware write protected. Only the sections of the memory array that are not block protected can be written. Hardware write protection is disabled when either WP pin is high or the WPEN bit is zero.

**DEVICE OPERATION**

**Write Enable and Disable**

The CAT25C08/16 contains a write enable latch. This latch must be set before any write operation. The device powers up in a write disable state when V<sub>CC</sub> is applied. WREN instruction will enable writes (set the latch) to the device. WRDI instruction will disable writes(reset the latch) to the device. Disabling writes will protect the device against inadvertent writes.

**READ Sequence**

The part is selected by pulling CS low. The 8-bit read instruction is transmitted to the CAT25C08/16, followed by the 16-bit address for 25C08/16. (only 10-bit addresses are used for 25C08, 11-bit addresses are used for 25C16. The rest of the bits are don't care bits).

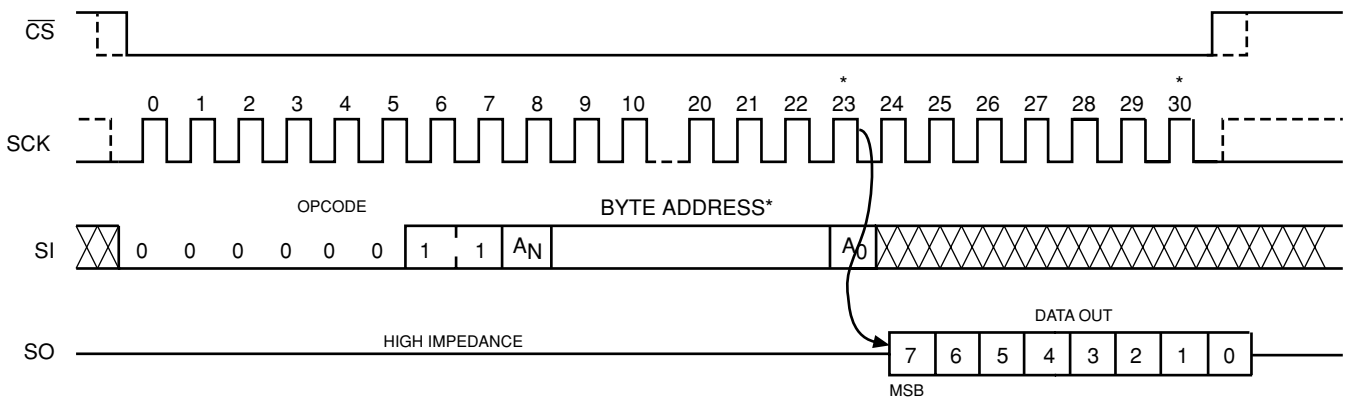
After the correct read instruction and address are sent, the data stored in the memory at the selected address is shifted out on the SO pin. The data stored in the memory at the next address can be read sequentially by continuing to provide clock pulses. The internal address pointer

is automatically incremented to the next higher address after each byte of data is shifted out. When the highest address is reached, the address counter rolls over to 0000h allowing the read cycle to be continued indefinitely. The read operation is terminated by pulling the CS high. To read the status register, RDSR instruction should be sent. The contents of the status register are shifted out on the SO line. The status register may be read at any time even during a write cycle. Read sequece is illustrated in Figure 4. Reading status register is illustrated in Figure 5.

**WRITE Sequence**

The CAT25C08/16 powers up in a Write Disable state. Prior to any write instructions, the WREN instruction must be sent to CAT25C08/16. The device goes into Write enable state by pulling the CS low and then clocking the WREN instruction into CAT25C08/16. The CS must be brought high after the WREN instruction to enable writes to the device. If the write operation is initiated immediately after the WREN instruction without CS being brought high, the data will not be written to the array because the write enable latch will not have been properly set. Also, for a successful write operation the address of the memory location(s) to be programmed must be outside the protected address field location selected by the block protection level.

**Figure 4. Read Instruction Timing**



\*Please check the Byte Address Table.

Note: Dashed Line= mode (1, 1) - - - -

**Byte Write**

Once the device is in a Write Enable state, the user may proceed with a write sequence by setting the  $\overline{CS}$  low, issuing a write instruction via the SI line, followed by the 16-bit address for 25C08/16. (only 10-bit addresses are used for 25C08, 11-bit addresses are used for 25C16. The rest of the bits are don't care bits). Programming will start after the  $\overline{CS}$  is brought high. Figure 6 illustrates byte write sequence. During an internal write cycle, all commands will be ignored except the RDSR (Read Status Register) instruction.

The Status Register can be read to determine if the write cycle is still in progress. If Bit 0 of the Status Register is set at 1, write cycle is in progress. If Bit 0 is set at 0, the device is ready for the next instruction

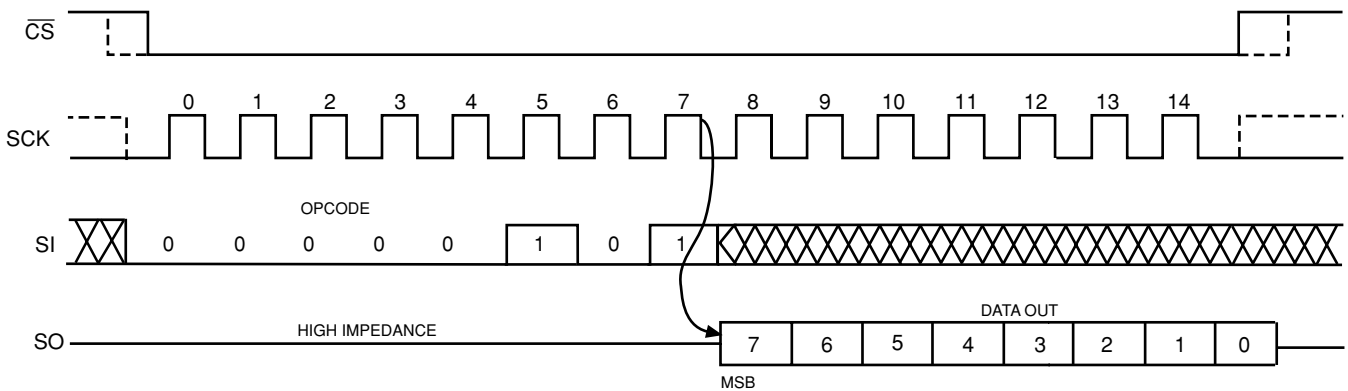
**Page Write**

The CAT25C08/16 features page write capability. After the initial byte, the host may continue to write up to 32

bytes. After each byte of data received, lower order address bits are internally incremented by one; the high order bits of address will remain constant. The only restriction is that the 32 bytes must reside on the same page. If the address counter reaches the end of the page and clock continues, the counter will “roll over” to the first address of the page and overwrite any data that may have been written. The CAT25C08/16 is automatically returned to the write disable state at the completion of the write cycle. Figure 8 illustrates the page write sequence.

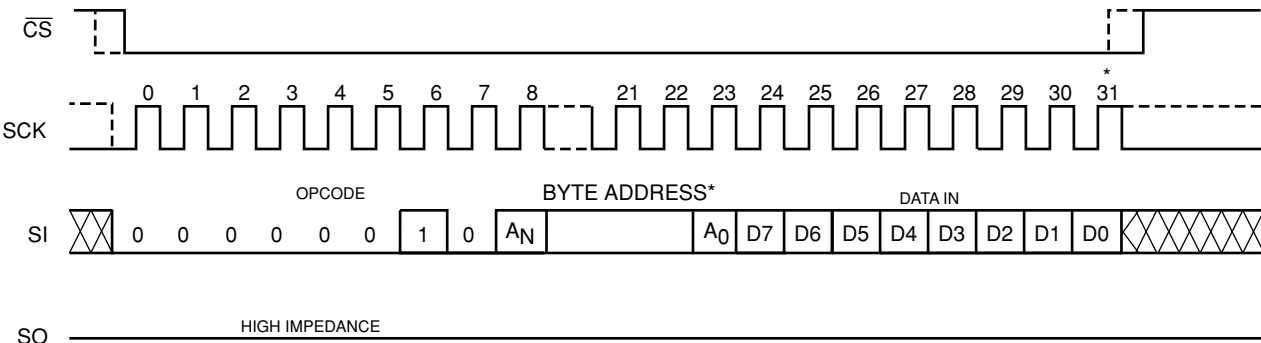
To write to the status register, the WRSR instruction should be sent. Only Bit 2, Bit 3 and Bit 7 of the status register can be written using the WRSR instruction. Figure 7 illustrates the sequence of writing to status register.

**Figure 5. RDSR Instruction Timing**



Note: Dashed Line= mode (1, 1) -----

**Figure 6. Write Instruction Timing**



\*Please check the Byte Address Table

Note: Dashed Line= mode (1, 1) -----



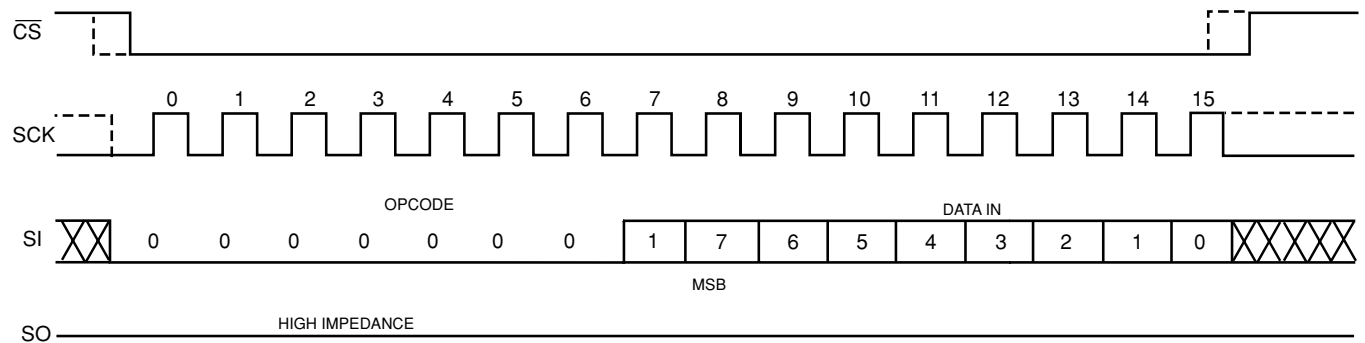
**DESIGN CONSIDERATIONS**

The CAT25C08/16 powers up in a write disable state and in a low power standby mode. A WREN instruction must be issued to perform any writes to the device after power up. Also, on power up  $\overline{CS}$  should be brought low to enter a ready state and receive an instruction. After a successful byte/page write or status register write, the CAT25C08/16 goes into a write disable mode.  $\overline{CS}$  must be set high after the proper number of clock cycles to start an internal write cycle. Access to the array during an internal write cycle is ignored and programming is continued. On power up, SO is in a high impedance. If an invalid op code is received, no data will be shifted

into the CAT25C08/16, and the serial output pin (SO) will remain in a high impedance state until the falling edge of  $\overline{CS}$  is detected again.

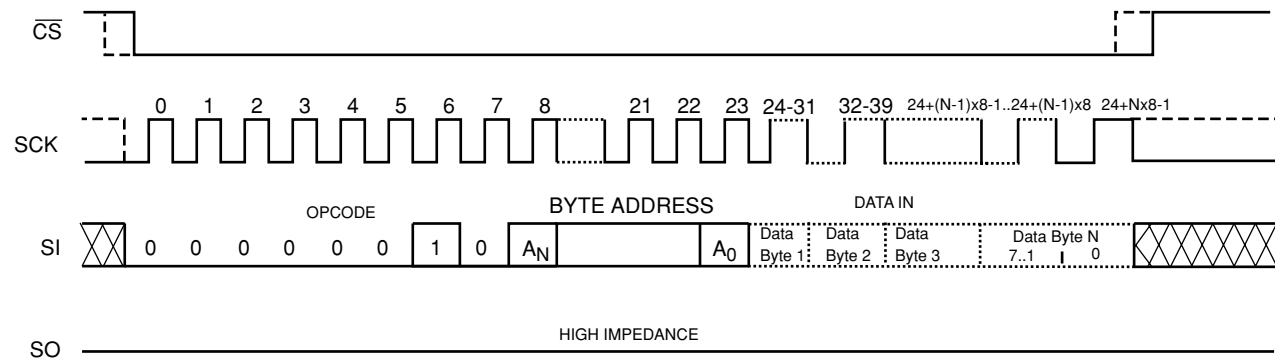
When powering down, the supply should be taken down to 0V, so that the CAT25C08/16 will be reset when power is ramped back up. If this is not possible, then, following a brown-out episode, the CAT25C08/16 can be reset by refreshing the contents of the Status Register (See Application Note AN10).

**Figure 7. WRSR Timing**



Note: Dashed Line= mode (1, 1) -----

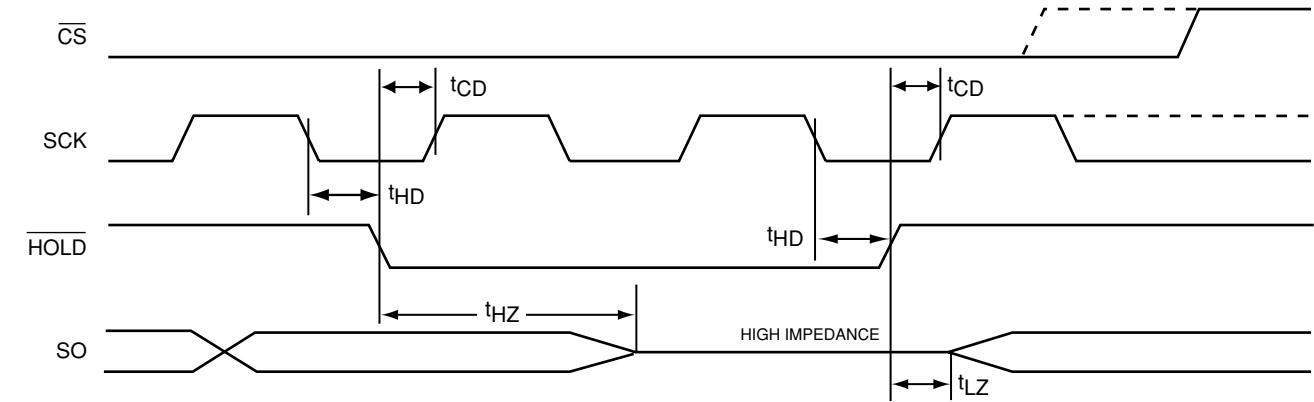
**Figure 8. Page Write Instruction Timing**



\*Please check the Byte Address Table.

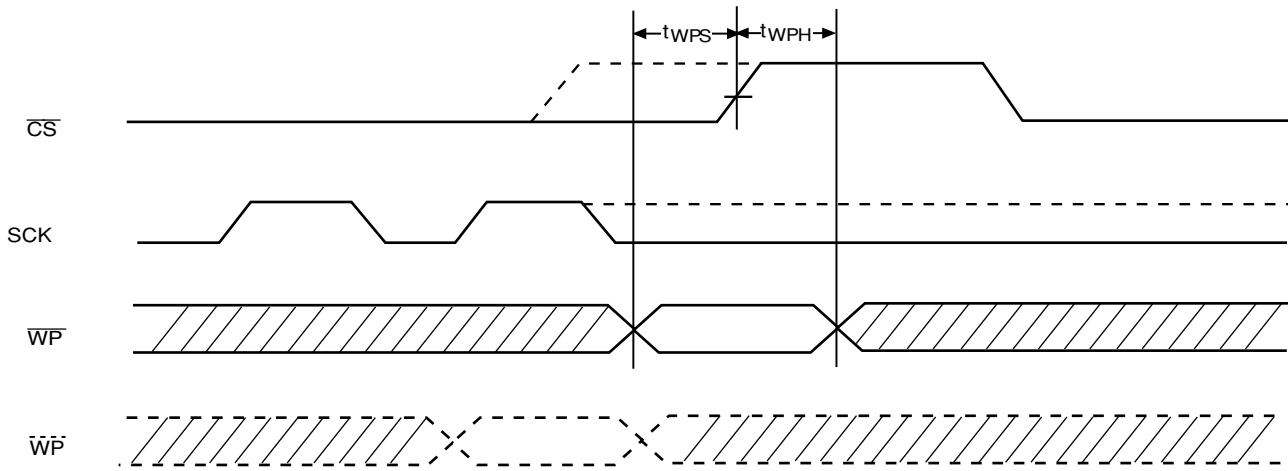
Note: Dashed Line= mode (1, 1) -----

**Figure 9.  $\overline{\text{HOLD}}$  Timing**



Note: Dashed Line= mode (1, 1) -----

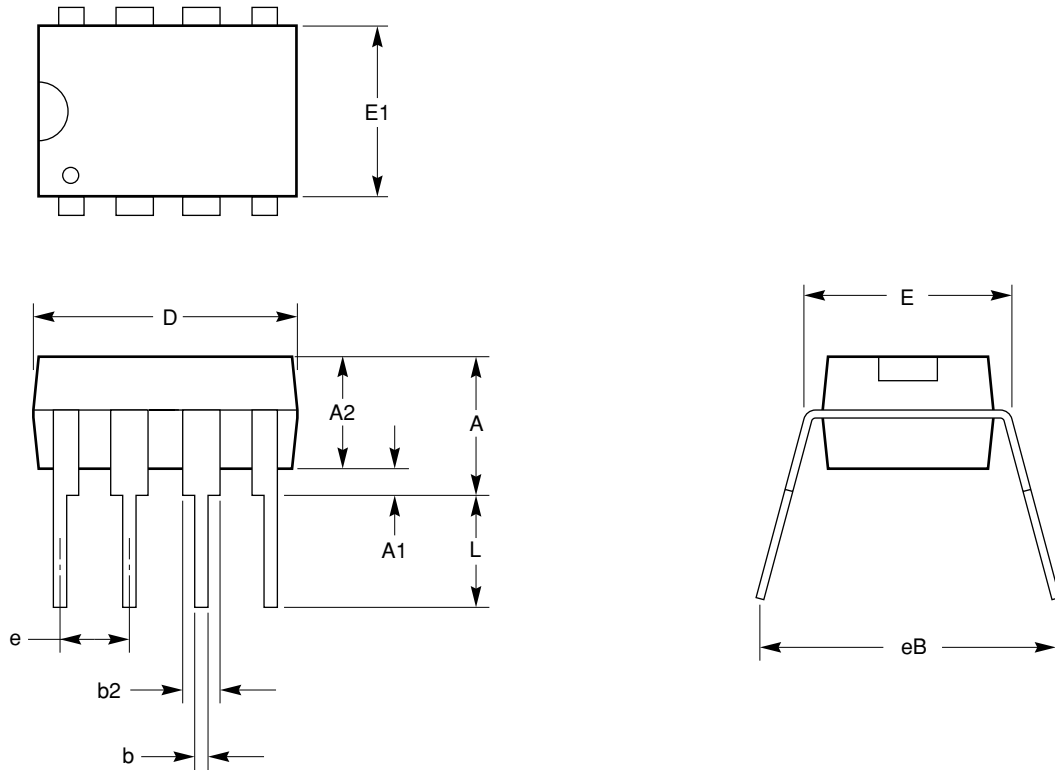
**Figure 10.  $\overline{\text{WP}}$  Timing**



Note: Dashed Line= mode (1, 1) -----

**PACKAGE INFORMATION**

**8-LEAD 300 MIL WIDE PLASTIC DIP (P, L)**

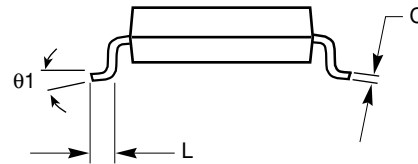
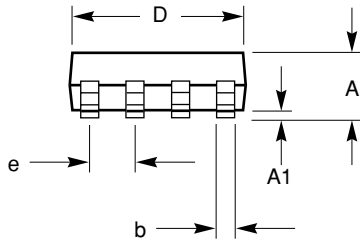
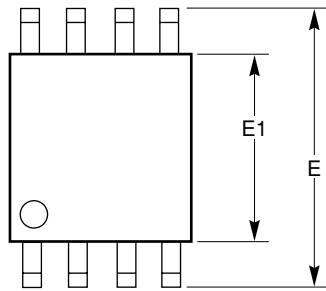


SYMBOL	MIN	NOM	MAX
A	0.120		0.210
A1	0.015		
A2	0.115	0.130	0.195
b	0.014	0.018	0.022
b2	0.045	0.060	0.070
D	0.355	0.365	0.400
D2	0.300		0.325
E	0.300	0.310	0.325
E1	0.240	0.250	0.280
e		0.100 BSC	
eB			0.430
L	0.115	0.130	0.150

Notes:

1. Complies with JEDEC Standard MS001.
2. All dimensions are in inches.
3. Dimensioning and tolerancing per ANSI Y14.5M-1982

**8-LEAD 150 MIL WIDE SOIC (S, V)**

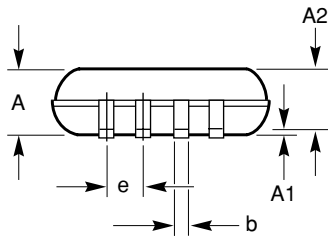
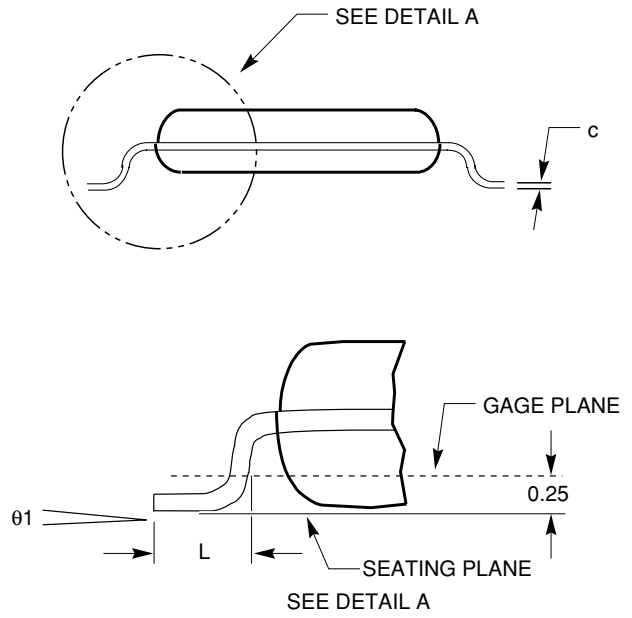
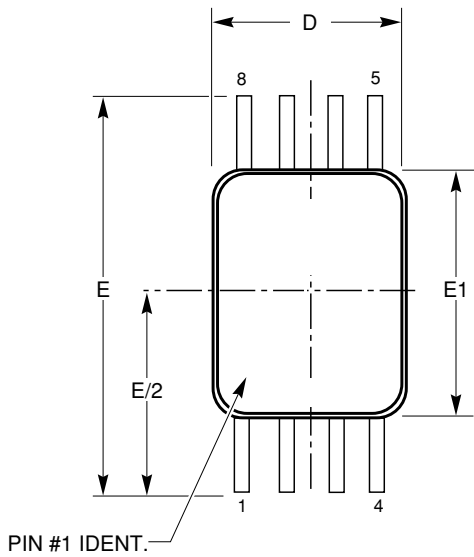


SYMBOL	MIN	NOM	MAX
A1	0.0040		0.0098
A2	0.0532		0.0688
b	0.013		0.020
C	0.0075		0.0098
D	0.1890		0.1968
E	0.2284		0.2440
E1	0.149		0.1574
e		0.050 BSC	
f	0.0099		0.0196
$\theta 1$	0°		8°

Notes:

1. Complies with JEDEC specification MS-012 dimensions.
2. All linear dimensions in millimeters.

### 8-LEAD TSSOP (U, Y)



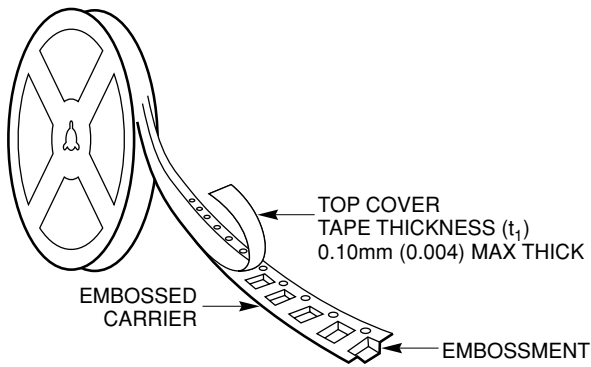
SYMBOL	MIN	NOM	MAX
A			1.20
A1	0.05		0.15
A2	0.80	0.90	1.05
b	0.19		0.30
c	0.09		0.20
D	2.90	3.00	3.10
E	6.30	6.4	6.50
E1	4.30	4.40	4.50
e		0.65 BSC	
L	0.50	0.60	0.75
$\theta1$	0.00		8.00

**Notes:**

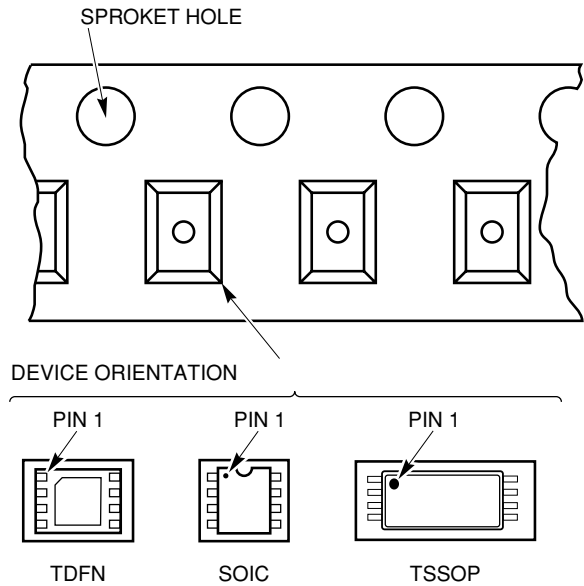
1. All dimensions in millimeters.

## TAPE AND REEL

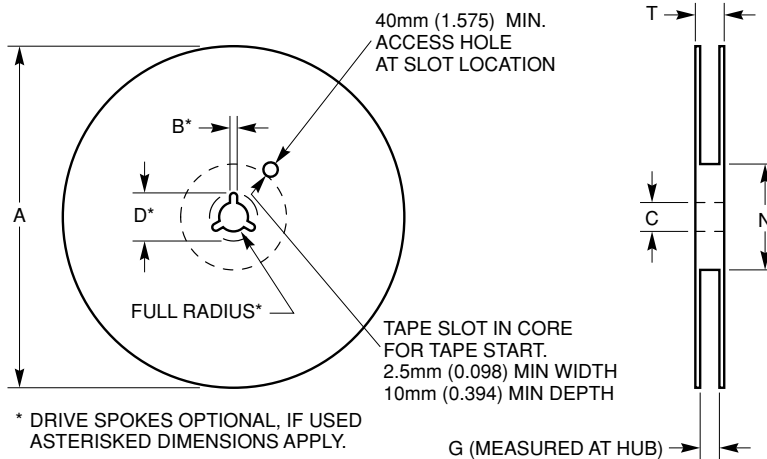
### Direction of Feed



### Device Orientation



### Reel Dimensions<sup>(1)</sup>



### Embossed Carrier Dimensions

TAPE SIZE	A		B MIN	C	D* MIN	N MIN	G	T MAX
	MAX	QTY/REEL						
12MM	330 (13.00)	3000	1.5 (0.059)	12.80 (0.504) 13.20 (0.5200)	20.2 (0.795)	50 (1.969)	12.4 (0.488) 14.4 (0.558)	18.4 (0.724)

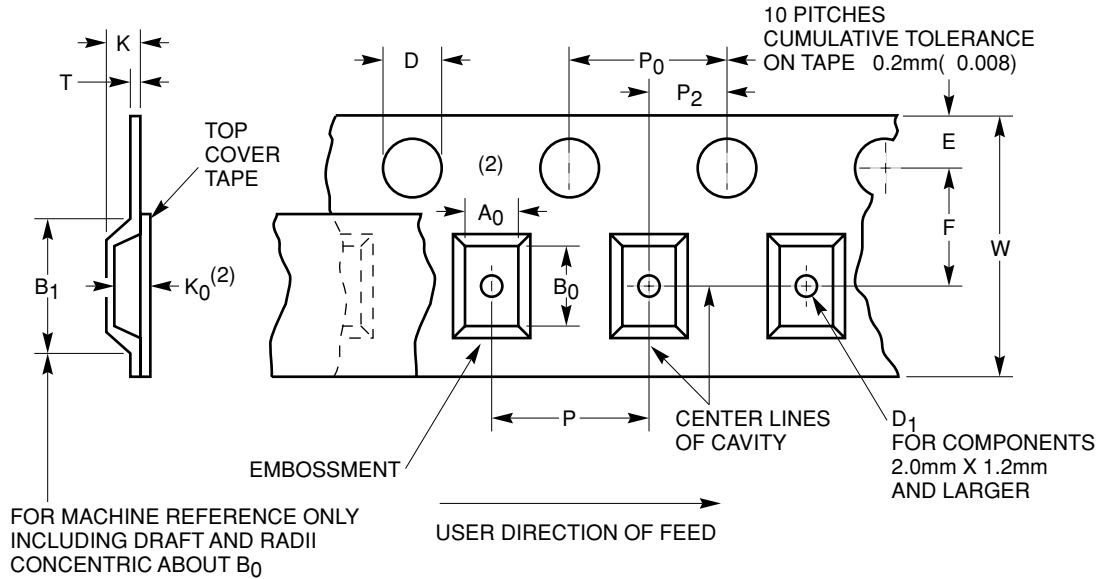
### Component/Tape Size Cross-Reference

Component	Package Type	Tape Size (W)	Part Pitch (P)
8L SOIC, TSSOP	V, Y, S, U	12mm	8mm

Notes:

(1) Metric dimensions will govern; English measurements rounded, for reference only and in parentheses.

**Embossed Carrier Dimensions (12 Pape Only)**



**Embossed Tape—Constant Dimensions<sup>(1)</sup>**

Tape Sizes	D	E	P <sub>0</sub>	T Max.	D1 Min.	A <sub>0</sub> B <sub>0</sub> K <sub>0</sub> <sup>(2)</sup>
12mm	<u>1.5 (0.059)</u>	<u>1.65 (0.065)</u>	<u>3.9 (0.153)</u>	400 (0.016)	1.5 (0.059)	
	1.6 (0.063)	1.85 (0.073)	4.1 (0.161)			

**Embossed Tape—Variable Dimensions<sup>(1)</sup>**

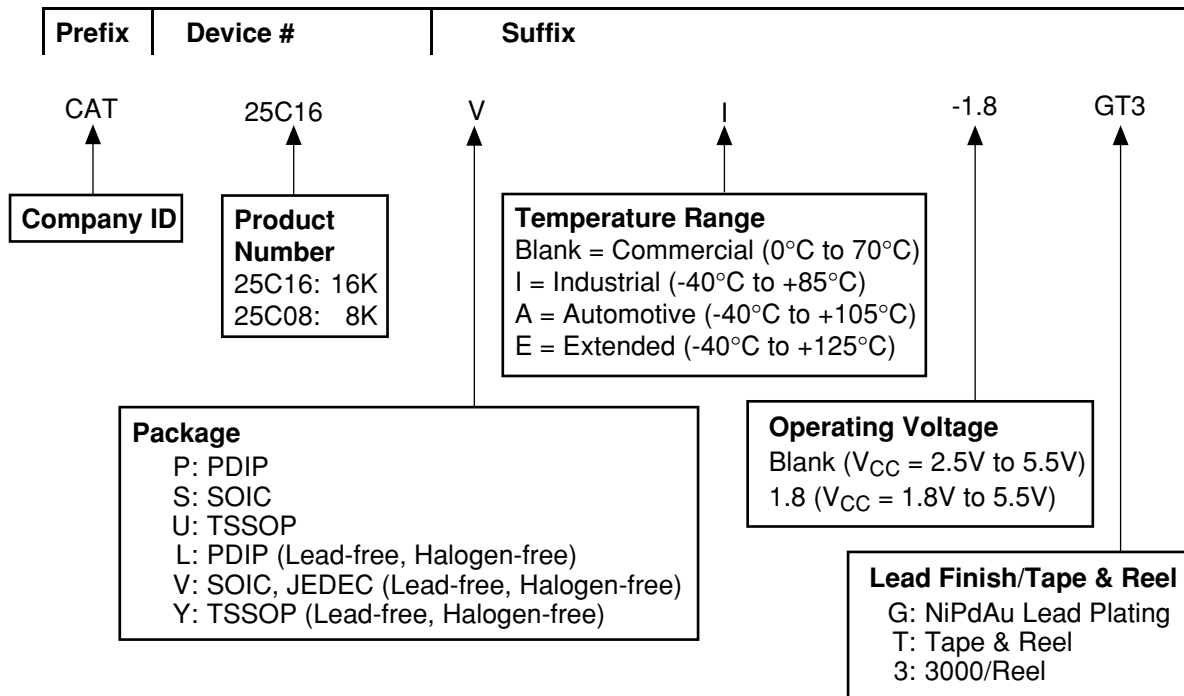
Tape Sizes	B <sub>1</sub> Max.	F	K Max.	P <sub>2</sub>	R Min.	W	P
12mm	8.2 (0.0323)	<u>5.45 (0.0215)</u>	4.5 (0.177)	<u>1.95 (0.077)</u>	30 (1.181)	<u>11.7 (0.460)</u>	<u>7.9 (0.275)</u>
		5.55 (0.0219)		2.05 (0.081)		12.3 (0.484)	8.1 (0.355)

Note:

(1) Metric dimensions will govern; English measurements rounded, for reference only and in parentheses.

(2) A<sub>0</sub> B<sub>0</sub> K<sub>0</sub> are determined by component size. The clearance between the component and the cavity must be within 0.05 (0.002) min. to 0.65 (0.026) max. for 12mm tape, 0.05 (0.002) min. to 0.90 (0.035) max. for 16mm tape, and 0.05 (0.002) min. to 1.00 (0.039) max. for 24mm tape and larger. The component cannot rotate more than 20° within the determined cavity, see Component Rotation.

**ORDERING INFORMATION**



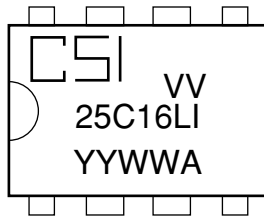
**Notes:**

(1) The device used in the above example is a 25C16VI-1.8GT3 (SOIC, Industrial Temperature, 1.8 Volt to 5.5 Volt Operating Voltage, Tape & Reel)



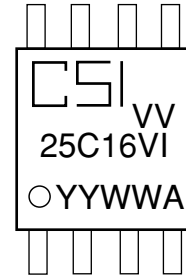
## PACKAGE MARKING

### 8-Lead PDIP



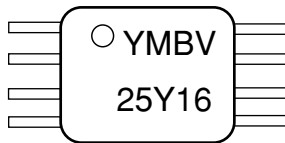
CSI = Catalyst Semiconductor, Inc.  
 25C16L = Device Code  
     25C08L  
     25C16L  
 I = Temperature Range  
 YY = Production Year  
 WW = Production Week  
 A = Product Revision  
 VV = Voltage Range  
     1.8V - 5.5V = 18  
     2.5V - 5.5V = Blank

### 8-Lead SOIC



CSI = Catalyst Semiconductor, Inc.  
 25C16V = Device Code  
     25C08V  
     25C16V  
 I = Temperature Range  
 YY = Production Year  
 WW = Production Week  
 A = Product Revision  
 VV = Voltage Range  
     1.8V - 5.5V = 18  
     2.5V - 5.5V = Blank

### 8-Lead TSSOP



Y = Production Year  
 M = Production Month  
 A = Die Revision  
 25Y16 = Device Code  
     25Y08  
     25Y16  
 I = Industrial Temperature Range  
 V = Voltage Range  
     1.8V - 5.5V = 8  
     2.5V - 5.5V = Blank

## REVISION HISTORY

Date	Rev.	Reason
03/21/2006	A	Initial Issue

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Catalyst Semiconductor, Inc.  
Corporate Headquarters  
1250 Borregas Avenue  
Sunnyvale, CA 94089  
Phone: 408.542.1000  
Fax: 408.542.1200  
www.catsemi.com

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